L Number	Hits	Search Text	DB	Time stamp
1	231461	(cihp or die or device) and (@ad<20010427) and (encapsulant or encapsulation or mold or molding)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/29 11:03
2	239600	(chip or die or device) and (@ad<20010427) and (encapsulant or encapsulation or mold or molding)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/29 13:11
3	6407	((chip or die or device) and (@ad<20010427) and (encapsulant or encapsulation or mold or molding)) and ((grind or grinding or polish or polishing ro cmp) same (chip or die or encapsulant or encapsulation or mold or molding))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/29 12:50
4	6407	(((chip or die or device) and (@ad<20010427) and (encapsulant or encapsulation or mold or molding)) and ((grind or grinding or polish or polishing ro cmp) same (chip or die or encapsulant or encapsulation or mold or molding))) and (@ad<20010427)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/29 13:12
5	6333	((chip or die or device) and (@ad<20010427) and· (encapsulant or encapsulation or mold or molding)) and ((grind or grinding or polish or polishing or cmp) same (chip or die or encapsulant or encapsulation or mold or molding))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/29 12:50
6	3477	((chip or die or device) and (@ad<20010427) and (encapsulant or encapsulation or mold or molding)) and ((grind or grinding or polish or polishing or cmp) with (chip or die or encapsulant or encapsulation or mold or molding))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/29 11:15
7	663	(((chip or die or device) and (@ad<20010427) and (encapsulant or encapsulation or mold or molding)) and ((grind or grinding or polish or polishing or cmp) with (chip or die or encapsulant or encapsulation or mold or molding))) and semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/29 11:16
8	710	(((chip or die or device) and (@ad<20010427) and (encapsulant or encapsulation or mold or molding)) and ((grind or grinding or polish or polishing or cmp) with (chip or die or encapsulant or encapsulation or mold or molding))) and (semiconductor or ic)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/29 12:52
9	1	(batch adj transfer) and ((grind or grinding or polish or polishing or cmp) same (chip or die or encapsulant or encapsulation or mold or molding))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/29 12:51
10	5858	(batch or transfer) and ((grind or grinding or polish or polishing or cmp) same (chip or die or encapsulant or encapsulation or mold or molding))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/29 12:51
11	4221	((batch or transfer) and ((grind or grinding or polish or polishing or cmp) same (chip or die or encapsulant or encapsulation or mold or molding))) and (@ad<20010427)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/29 12:52

12	1162	(((batch or transfer) and ((grind or grinding or polish or polishing or cmp) same (chip or die or encapsulant or encapsulation or mold or molding))) and (@ad<20010427)) and (semiconductor or ic)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/29 12:52
13	875	((((batch or transfer) and ((grind or grinding or polish or polishing or cmp) same (chip or die or encapsulant or encapsulation or mold or molding))) and (@ad<20010427)) and (semiconductor or ic)) not ((((chip or die or device) and (@ad<20010427 and (encapsulant or encapsulation or mold or molding)) and ((grind or grinding or polish or polishing or cmp) with (chip or die or encapsulant or encapsulation or mold or molding))) and semiconductor)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/29 12:53
14	1943	(different near (chips or dies or devices)) and (@ad<20010427) and (encapsulant or encapsulation or mold or molding)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/29 13:12
15	24	((different near (chips or dies or devices)) and (@ad<20010427) and (encapsulant or encapsulation or mold or molding)) and 257/778.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/29 13:14
16	24	(((different near (chips or dies or devices)) and (@ad<20010427) and (encapsulant or encapsulation or mold or molding)) and 257/778.ccls.) and (@ad<20010427)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/29 13:13
17	172	((different near (chips or dies or devices)) and (@ad<20010427) and (encapsulant or encapsulation or mold or molding)) and flip	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/29 13:15
18	152	(((different near (chips or dies or devices)) and (@ad<20010427) and (encapsulant or encapsulation or mold or molding)) and flip) not (((different near (chips or dies or devices)) and (@ad<20010427) and (encapsulant or encapsulation or mold or molding)) and 257/778.ccls.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/29 13:15